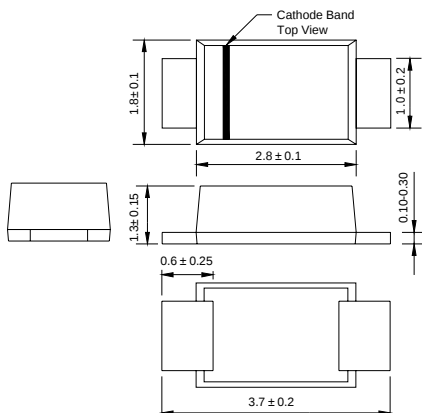


SOD-123FL



Dimensions in millimeters

FEATURES

- ◆ Glass passivated device
- ◆ Ideal for surface mounted applications
- ◆ Low reverse leakage
- ◆ Metallurgically bonded construction
- ◆ High temperature soldering guaranteed:
250°C/10 seconds, 0.375" (9.5mm) lead length,
5 lbs. (2.3kg) tension

MECHANICAL DATA

Case: JEDEC SOD-123FL molded plastic body over passivated chip
Terminals: Plated axial leads, solderable per MIL-STD-750, Method 2026
Polarity: Color band denotes cathode end
Mounting Position: Any
Weight: 0.0007 ounce, 0.02 grams

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Catalog Number	SYMBOLS	ES1A E1A	ES1B E1B	ES1C E1C	ES1D E1D	ES1E E1E	ES1G E1G	ES1J E1J	UNITS
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	150	200	300	400	600	VOLTS
Maximum RMS voltage	V _{RMS}	35	70	105	140	210	280	420	VOLTS
Maximum DC blocking voltage	V _{DC}	50	100	150	200	300	400	600	VOLTS
Maximum average forward rectified current	I _(AV)	1.0							Amp
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	25.0							Amps
Maximum instantaneous forward voltage at1.0A	V _F	0.95				1.25		1.7	Volts
Maximum DC reverse current T _A =25°C at rated DC blocking voltage T _A =100°C	I _R	5.0 100.0							μA
Maximum reverse recovery time (NOTE 1)	trr	35							ns
Typical junction capacitance (NOTE 2)	C _J	10							pF
Typical thermal resistance (NOTE 3)	R _{θJA}	85							K/W
Operating junction and storage temperature range	T _J ,T _{STG}	-55 to +150							°C

Note: 1. Measured with $I_F=0.5\text{A}$, $I_R=1\text{A}$, $I_{rr}=0.25\text{A}$.
2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
3. PCB mounted on 0.2*0.2" (5.0*5.0mm) copper pad area.

RATINGS AND CHARACTERISTIC CURVES

FIG. 1- FORWARD CURRENT DERATING CURVE

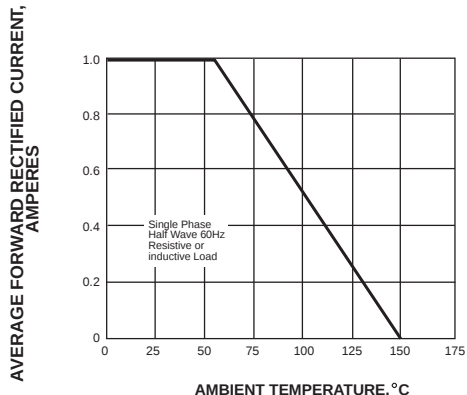


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

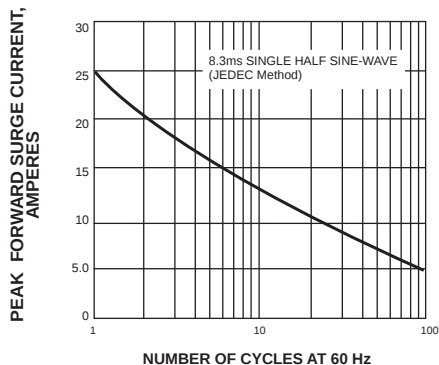


FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

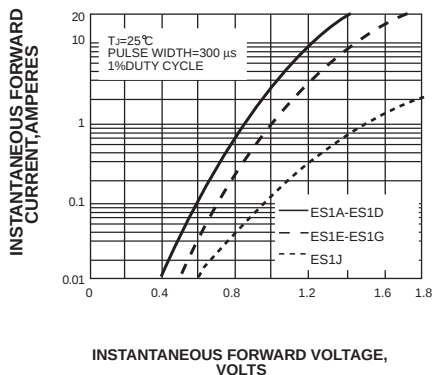


FIG. 4-TYPICAL REVERSE CHARACTERISTICS

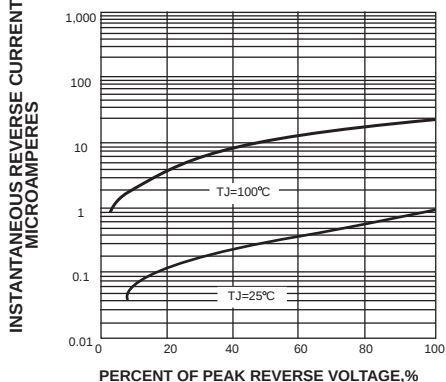


FIG. 5-TYPICAL JUNCTION CAPACITANCE

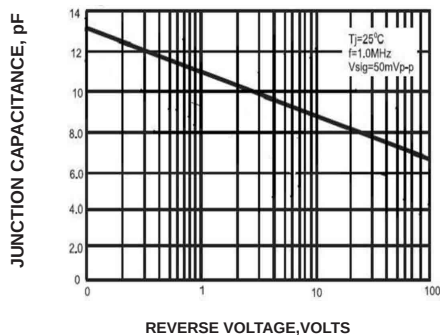


FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE

